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**Amendments to the Specification:**

Please replace the sentence at page 4, line 14, with the following rewritten sentence:

-- The airflow cools an electronic device 105 attached to the contact surface 102 of the heat sink 100 by dissipating the heat conducted through heat sink 100 and accumulated in fins 104.--

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Please replace the sentence at page 4, line 14, with the following rewritten sentence:

--This variation is shown in **FIG. 4** as one side 404 of the closed end of flexible channel 303 having been compressed ~~more~~ less than the other side 405.—

Please replace the paragraph at page 19, line 6, with the following rewritten paragraph:

--**FIG. 9** is a cross-sectional view of another cooling device 900 having a wick 302 902 therein and having flexible channels 903A and 903B attached thereto, according to another embodiment of the invention. In **FIG. 9**, conduit 301 is positioned above IC's 910 and 911, which are mounted on a PCB 920. In this embodiment, conduit 301 is a heat pipe, e.g. a tubular structure containing a wick 302 902 and coupled with a reservoir 930. Reservoir 930 may be mounted on or within conduit 301, or may be external to conduit 301 as shown in **FIG. 9**. If external, a pump 932 and a connector (e.g. tube or hose) 933 may be provided to couple reservoir 930 with conduit 301. Reservoir 930 may contain a liquid coolant 931 such as water or similar coolants. The coolant 931 is conveyed by capillary action through wick 302 902 until it is vaporized by the heat transferred through flexible channels 903A and 903B from IC's 810 and 811 (or other electronic or electrical devices). As the vapor reaches cooler portions of heat pipe 301 (e.g. a heat sink attached to heat pipe 301), it cools, condenses, and the condensation is again conveyed by capillary action through wick 302 902 to flexible channels 903A and 903B.--